12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250416002.1
Wafer Diameter Change for Select Devices in the LBC4 Process at DFAB
Change Notification / Sample Request

Date: April 16, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) process.

TI requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 60 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

Changes outlined in this notification underscore our commitment to product longevity and supply continuity, as well as our continued efforts to transition to newer, more efficient manufacturing processes and technologies. Specifically, this particular notification is related to TI's multiyear transition plan for our two remaining 150-millimeter production lines (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). SFAB closure activities are expected to begin by the end of 2025. DFAB will remain open with a smaller set of 200mm technologies and GaN.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20250416002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS65130RGER	TPS65130RGER
TPS65131RGER	TPS65131RGER

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250416002.1	**PCN Date:**	April 16, 2025
Title:	Wafer Diameter Change for Select Devices in the LBC4 Process at DFAB		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	July 15, 2025	**Sample requests accepted until:**	June 15, 2025*

***Sample requests received after June 15, 2025 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

This change notification is to announce a wafer diameter change only for the select devices in the LBC4 process at DFAB. This is not a fab site change.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
DFAB	LBC4	150 mm	DFAB	LBC4	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

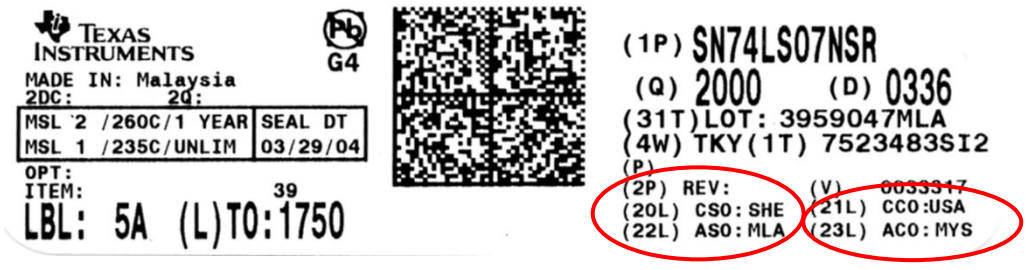
Changes to product identification resulting from this PCN:

Note: This is not a Fab site change. The 6” line and 8” line are in the same location.

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas

Sample product shipping label (not actual product label):



Product Affected:

TPS65130RGER	TPS65131RGER

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS65130RGER	Qual Device: TPS65131RGER	QBS Reference: SN65HVD233QDRQ1	QBS Reference: TRS3223QPWRQ1	QBS Reference: TPS65131TRGERQ1
ESD	E2	ESD CDM	-	1000 Volts	-	-	1/3/0	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	12000 Volts	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	15000 Volts	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	16000 Volts	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	3000 Volts	-	-	1/3/0	1/3/3	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/6[1]	1/6/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/1/0	1/1/0	-	-	1/1/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TPS65130RGER is qualified at MSL2 260C
- Qual Device TPS65131RGER is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2406-007

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.